

ABSTRACT OF THE DISCLOSURE

Miniaturization and lighter weight is carried out for a condenser microphone, whereby a condenser microphone 10A of the present invention is structured to include: a semiconductor device 20A including a conductive pattern 11, a semiconductor element 12 placed on the conductive pattern 11, and a sealing resin 13 for integrally sealing the conductive pattern 11 and the semiconductor element 12; a fixed electrode layer 14 that is electrically connected to the semiconductor element 12 and that is formed on the surface of the sealing resin 13 to form one electrode of the condenser; and a vibration film 21 that is provided to be opposed to the fixed electrode layer 14 and that forms another electrode of the condenser.

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